SS32 THRU SS3200

Reverse Voltage - 20 to 200 Volts Forward Current - 3.0 Ampere

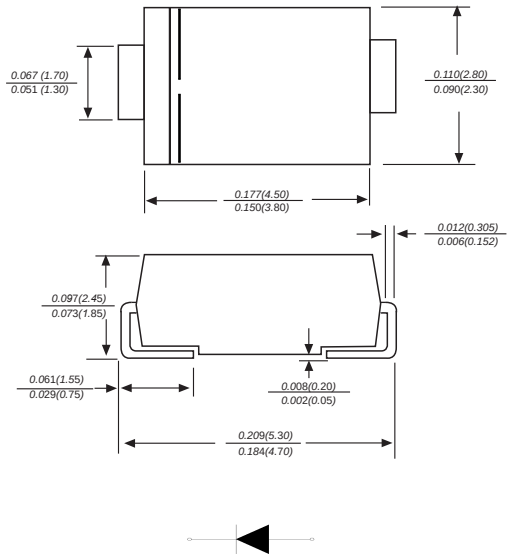
SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction,majority carrier conduction
- Low power loss,high efficiency
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250 °C/10 seconds at terminals

DO-214AC/SMA

RoHS COMPLIANT



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC DO-214AC/SMA molded plastic body
Terminals : Solderable per MIL-STD-750,Method 2026
Polarity : Color band denotes cathode end Mounting Position : Any
Weight : 0.0018 ounce, 0.064 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter / Marking Code	SYMBOLS	MDD SS32	MDD SS33	MDD SS34	MDD SS35	MDD SS36	MDD SS38	MDD SS310	MDD SS3150	MDD SS3200	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	$I_{(AV)}$	3.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I_{FSM}	80									A
Maximum instantaneous forward voltage at 3.0A	V_F	0.55			0.70		0.85			0.95	V
Maximum DC reverse current T_A=25℃	I_R	0.5					0.3				mA
at rated DCblocking voltage T_A=125℃		5					3.0				
Typical junction capacitance (NOTE 1)	C_J	250			180						pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	70									℃/W
Operating junction temperature range	T_J	-55 to +125									℃
Storage temperature range	T_{STG}	-55 to +150									℃

Note: 1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

Typical Characterisitics

Fig.1 Forward Current Derating Curve

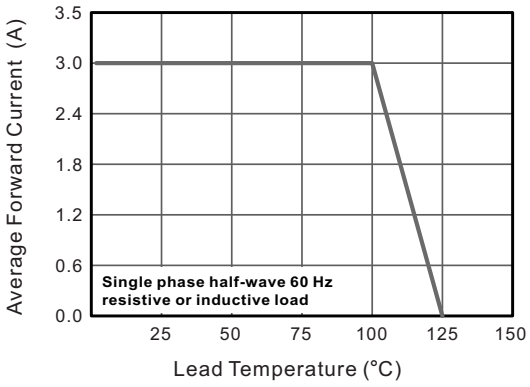


Fig.2 Typical Reverse Characteristics

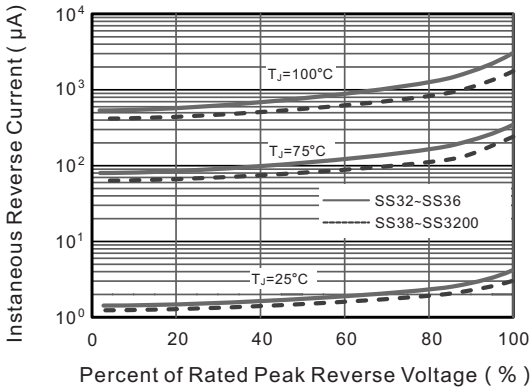


Fig.3 Typical Forward Characteristic

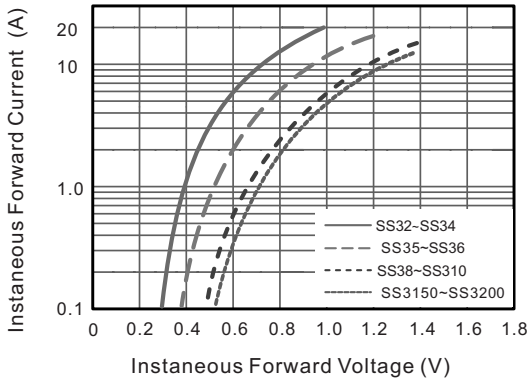


Fig.4 Typical Junction Capacitance

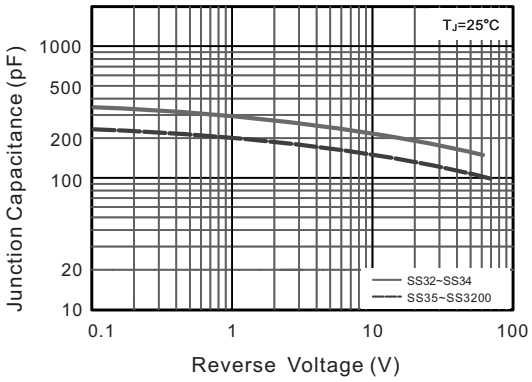


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

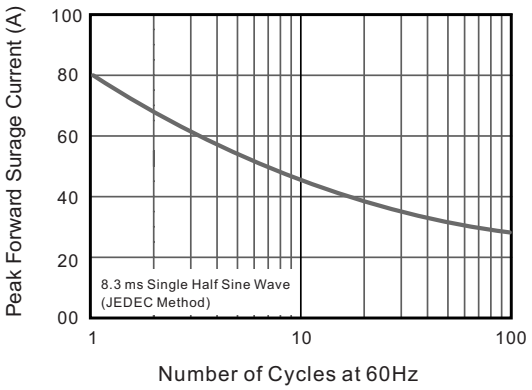
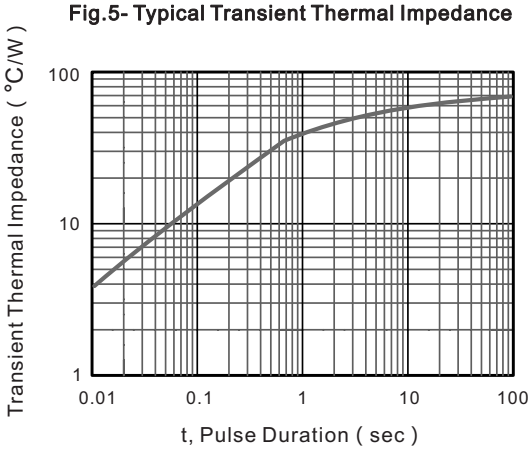
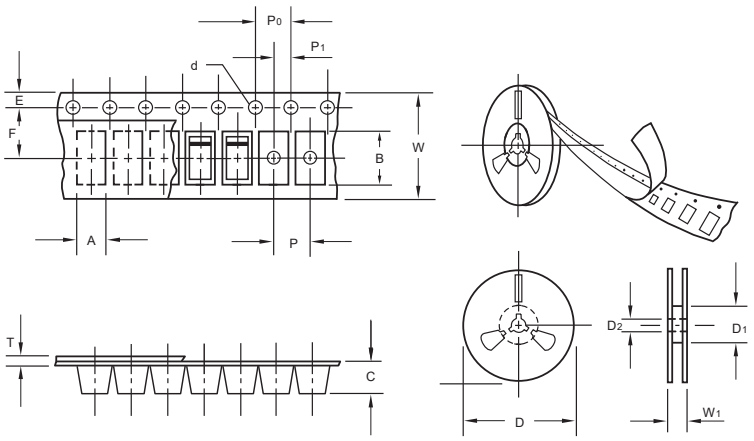


Fig.5- Typical Transient Thermal Impedance



The curve above is for reference only.

Packing information



unit:mm

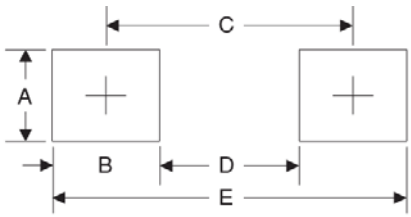
Item	Symbol	Tolerance	SMA
Carrier width	A	0.1	2.80
Carrier length	B	0.1	5.33
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D_1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D_1	min	62.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.28
Tape width	W	0.3	12.00
Reel width	W_1	1.0	18.00

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
SMA	13"	5,000	4.0	10,000	340*350*40	330	370*370*370	80,000

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.68	0.066
B	1.52	0.060
C	3.93	0.154
D	2.41	0.095
E	5.45	0.215

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